# <span id="page-0-0"></span>**Multiscale calculations of thermoelectric properties of** *n***-type**  $Mg_2Si_{1-x}Sn_x$  **solid solutions**

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The band structure of  $Mg_2Si_{1-x}Sn_x$  solid solutions with  $0.250 \le x \le 0.875$  is calculated using the firstprinciples pseudopotential method. It is found that the low-lying light and heavy conduction bands converge and the effective mass reaches a maximum value near  $x = 0.625$ . Using the semiclassical Boltzmann transport theory and relaxation-time approximation, we find that the system with  $x = 0.625$  exhibits both higher Seebeck coefficient and higher electrical conductivity than other solid solutions at intermediate temperatures. By fitting first-principles total energy calculations, a modified Morse potential is constructed, which is used to predicate the lattice thermal conductivity via equilibrium molecular dynamics simulations. Due to relatively higher power factor and lower thermal conductivity, the  $Mg_2Si_{0.375}Sn_{0.625}$  is found to exhibit enhanced thermoelectric performance at 800 K, and additional Sb doping is considered in order to make a better comparison with experiment results.

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### **I. INTRODUCTION**

As fossil fuels are being exhausted and their burning contributes to the global warming, it is urgently needed to develop clean and renewable sources of energy. Thermoelectric materials have attracted much attention because they can directly convert heat into electricity and vice versa. Such materials utilize the Seebeck effect for power generation and the Peltier effect for refrigeration. The efficiency of a thermoelectric material is determined by the so-called figure of merit

$$
ZT = S^2 \sigma T / \kappa, \qquad (1)
$$

where *S* is the Seebeck coefficient,  $\sigma$  is the electrical conductivity, *T* is the absolute temperature, and  $\kappa$  is the thermal conductivity which contains both the lattice  $(\kappa_l)$  and electronic components  $(\kappa_e)$ . A high  $ZT$  value indicates good thermoelectric performance, and one therefore should try to increase the power factor ( $S^2\sigma$ ) and/or decrease the thermal conductivity  $(\kappa = \kappa_e + \kappa_l).$ <sup>[1](#page-8-0)</sup>

Intermetallic compounds  $Mg_2Si$ ,  $Mg_2Sn$ , and their solid solutions could be promising thermoelectric materials at intermediate temperature range between 500–800 K. These compounds contain nontoxic and environmentally friendly constituent elements that are inexpensive and abundant in the Earth's crust.<sup>[2,3](#page-8-0)</sup> Mg<sub>2</sub>Si can be readily *n*-type doped, and the usual donors are Bi and Sb. For example, Tani and Kido<sup>4</sup> fabricated the  $Mg_2SiBi_{0.02}$  sample which exhibited a  $ZT$  value of 0.86 at 862 K. Akasaka *et al.*[5](#page-8-0) obtained a *ZT* value of 0.65 at 840 K for the  $Mg_2Si:Bi_{0.01}$ . Bux *et al.*<sup>[6](#page-8-0)</sup> found a *ZT* value of 0.[7](#page-8-0) at 775 K for the  $Mg_2SiBi_{0.0015}$ . You *et al.*<sup>7</sup> prepared the  $Mg_2Si:Bi_{0.02}$  sample with a  $ZT$  value of 0.7 at 823 K. The Sb-doped sample  $Mg_2SiSb_{0.02}$  has a  $ZT$  value of 0.56 at [8](#page-8-0)62 K,<sup>8</sup> while the Mg<sub>2</sub>Si<sub>0.9</sub>Sb<sub>0.1</sub> shows a  $ZT$  value of 0.55 at 750 K.<sup>[9](#page-8-0)</sup> On the other hand, Zaitsev *et al.*<sup>[10](#page-8-0)</sup> investigated *n*-type Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions in a broad range of compositions, and found that the large atomic mass difference between Si and Sn dramatically reduces the thermal conductivity of the solid solutions, which leads to a high-*ZT* value of about 1.1 near 800 K. Isoda *et al.*[11](#page-8-0) obtained a *ZT* value of 0.87 at 630 K for the Bi-doped  $Mg_2Si_{0.5}Sn_{0.5}$ . Tani and Kido<sup>12</sup> found that the Al-doped  $Mg_2Si_{0.9}Sn_{0.1}$  shows a  $ZT$  value of 0.68 at 864 K, which is six times larger than that of the undoped solid solution. Luo *et al.*<sup>[13](#page-9-0)</sup> fabricated the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> (0 ≤ *x* ≤ 1.0) solid solutions and enhanced the *ZT* value to 0.1 at 490 K when  $x =$ 0.2. Liu *et al.*<sup>[14](#page-9-0)</sup> prepared the low-cost Sb-doped  $Mg_2Si_{0.6}Sn_{0.4}$ , and the *ZT* value can be reached to 1.11 at 860 K. Gao *et al.*[15](#page-9-0) reproducibly obtained *ZT* values larger than 0.9 at 780 K for their Sb-doped Mg<sub>2</sub>Si<sub>0.5</sub>Sn<sub>0.5</sub>. Based on the symmetry of energy bands of Mg2Si and Mg2Sn, Zaitsev *et al.*[10](#page-8-0) reasoned that for some particular content of Si and Sn, the two lowlying conduction bands of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions will coincide in energy but did not consider consequences of such a band convergence. Very recently, the positive effect of band convergence on the Seebeck coefficient and thus the overall thermoelectric performance of  $Mg_2Si_{1-r}Sn_r$  solid solutions was experimentally demonstrated by our team<sup>[16](#page-9-0)</sup> and yielded a *ZT* value of 1.3 around 750 K.

The above survey indicates that the measured *ZT* value of  $Mg_2Si-based$  materials varies in the range of 0.1–1.3 and depends on the condition of synthesis, alloying proportions, and doping levels. However, the bulk of these works were focused on experimental studies with little theoretical insight and guidance provided. In this work, we investigate the thermoelectric properties of *n*-type doped  $Mg_2Si_{1-x}Sn_x$  $(0.250 \le x \le 0.875)$  solid solutions by a multiscale approach, which includes first-principles calculations, semiclassical Boltzmann transport theory, and empirical molecular dynamics (MD) simulations. We shall see that the  $Mg_2Si_{1-x}Sn_x$  with  $x = 0.625$  exhibits the highest *ZT* value at 800 K due to the highest power factor and the lowest thermal conductivity, which suggests its promising thermoelectric applications.

The rest of this paper is organized as follows. Sec. [II](#page-1-0) gives the computational details of our multiscale approach. <span id="page-1-0"></span>In Sec. [III,](#page-2-0) we discuss the electronic, transport, and thermoelectric properties of *n*-type  $Mg_2Si_{1-x}Sn_x(0.250 \le x \le 0.875)$ solid solutions. A summary of our work is given in Sec. [IV.](#page-8-0)

## **II. METHOD OF CALCULATIONS**

### **A. First-principles calculations and Boltzmann theory**

The energy band-structure calculations have been performed using a first-principles plane-wave pseudopotential formulation<sup>[17–19](#page-9-0)</sup> within the framework of density functional theory (DFT). The exchange-correlation energy is in the form of Perdew-Wang-91 (Ref. [20\)](#page-9-0) with generalized gradient approximation (GGA). Ultrasoft pseudopotentials are used for the Mg, Si, and Sn atoms and the cutoff energy is set as 151 eV. During the geometry optimizations, both the atomic positions and the lattice constants are fully relaxed until the magnitude of the force acting on all atoms becomes less than  $0.01 \text{ eV/A}$ , which also converges the total energy within 1 meV. The irreducible Brillouin zone (IBZ) is sampled with  $10 \times 10 \times 10$ Monkhorst-Pack *k* meshes. The Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions are modeled by a rhombohedral  $2 \times 2 \times 2$  supercell which has eight equivalent positions for the Si or Sn atoms. The Sn concentration *x* can thus be 0.250, 0.375, 0.500, 0.625, 0.750, and 0.875, which are comparable to those measured in Ref. [16.](#page-9-0)

In a microscopic model of transport process, the Seebeck coefficient *S*, the electrical conductivity  $\sigma$ , and the electronic thermal conductivity *κe* can be derived from the calculated band structure in the IBZ. Here, we use a semiclassical approach by solving the Boltzmann's equation in the relaxationtime approximation. $21$  The kernel is to find the so-called transport distribution, which can be expressed as

$$
\Xi = \sum_{\vec{k}} \vec{v}_{\vec{k}} \vec{v}_{\vec{k}} \tau_{\vec{k}}, \tag{2}
$$

where  $\vec{v}$  and  $\tau$  are the group velocity and relaxation time at state  $\vec{k}$ , respectively. In principle, the relaxation time is energy dependent. However, it is usually reasonable to assume a constant  $\tau$  for transport properties since they involve the derivative of the Fermi function, which is significant only in a small energy window around the Fermi level and *τ* usually does not change much over this interval.<sup>22</sup> The Seebeck coefficient *S* and the electrical conductivity  $\sigma$  are given by

$$
\sigma = e^2 \int d\varepsilon \left( -\frac{\partial f_0}{\partial \varepsilon} \right) \Xi (\varepsilon), \tag{3}
$$

$$
S = \frac{ek_B}{\sigma} \int d\varepsilon \left( -\frac{\partial f_0}{\partial \varepsilon} \right) \Xi (\varepsilon) \frac{\varepsilon - \mu}{k_B T}, \tag{4}
$$

where  $f_0$  is the equilibrium Fermi function,  $k_B$  is the Boltzmann's constant, and  $\mu$  is the chemical potential. The electronic thermal conductivity *κe* is calculated according to the Wiedemann-Franz law<sup>23</sup>

$$
\kappa_e = L \sigma T,\tag{5}
$$

where *L* is the Lorenz number.

### **B. Empirical potential and molecular dynamics**

To study the phonon transport in the  $Mg_2Si_{1-x}Sn_x$  solid solutions, an accurate interatomic potential is necessary. We



FIG. 1. (Color online) The crystal structure of antifluorite compounds Mg<sub>2</sub>Si and Mg<sub>2</sub>Sn.

thus develop a modified Morse potential which contains the two-body bond and three-body angle interactions

$$
U = U_1 + U_2. \tag{6}
$$

Here, the two-body potential  $U_1$  is in the form of<sup>24</sup>

$$
U_1 = D\{[1 - e^{-a(r - r_0)}]^2 - 1\},\tag{7}
$$

where *D* is the depth of the potential well, *a* is the bond elasticity,  $r$  represents the interatomic separation, and  $r_0$  is the corresponding equilibrium distance. The three-body potential  $U_2$  is given by<sup>24</sup>

$$
U_2 = \frac{1}{2}k\left(\cos\theta - \cos\theta_0\right)^2,\tag{8}
$$

where  $k$  is the force constant,  $\theta$  represents the bond angle, and  $\theta_0$  is the corresponding angle at equilibrium. These potential parameters can be determined by fitting the energy surface from first-principles calculations.

The lattice thermal conductivity  $\kappa_l$  is then predicted using MD simulations combined with the Green-Kubo autocorrelation decay method. $24,25$  Such an approach can deal with phonon-phonon scattering and it is possible to obtain an accurate  $\kappa_l$  from the periodic unit cell much smaller than the phonon mean-free path. In this work, the time step is set as 0.5 fs, and the constant temperature simulation with periodic boundary conditions runs for 4 000 000 steps, giving a total time of 2.0 ns. The system reaches an equilibrium state and the temperature stabilizes around the set value after 0.5 ns. The data collection is performed from 0.5 to 2.0 ns and the

TABLE I. Calculated lattice constant  $a$  (in unit of  $\AA$ ), effective mass  $m^*$  (in terms of electron mass  $m_0$ ), and the energy difference  $\Delta E$ (in units of eV) between the two low-lying conduction bands  $(CB<sub>L</sub>)$ and  $CB_H$ ) for the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions.

|                  |      | $m^*$           |                 |            |  |
|------------------|------|-----------------|-----------------|------------|--|
| $\boldsymbol{x}$ | a    | CB <sub>L</sub> | CB <sub>H</sub> | $\Delta E$ |  |
| 0.000            | 6.35 |                 |                 |            |  |
| 0.250            | 6.46 | 0.19            | 0.38            | 0.30       |  |
| 0.375            | 6.52 | 0.24            | 0.43            | 0.18       |  |
| 0.500            | 6.59 | 0.26            | 0.43            | 0.11       |  |
| 0.625            | 6.64 | 0.20            | 0.61            | 0.038      |  |
| 0.750            | 6.70 | 0.25            | 0.52            | 0.15       |  |
| 0.875            | 6.76 | 0.28            | 0.37            | 0.27       |  |
| 1.000            | 6.81 |                 |                 |            |  |

<span id="page-2-0"></span>corresponding heat flux *J* is given by

$$
J = \sum_{i} \varepsilon_i v_i + \frac{1}{2} \sum_{i < j} [f_{ij} \cdot (v_i + v_j)] r_{ij}, \tag{9}
$$

where  $\varepsilon_i$  is the site energy of atom *i*,  $v_i$  and  $v_j$  are, respectively, the velocities of atoms  $i$  and  $j$ ,  $f_{ij}$  is their interaction force, and  $r_{ij}$  is their separation. The lattice thermal conductivity  $\kappa_l$ is thus obtained by

$$
\kappa_l = \frac{1}{3k_B T^2 V} \int_0^\infty \langle J(0) \cdot J(t) \rangle dt, \tag{10}
$$

where *V* is the volume of the simulation system, and  $\langle J(0) \cdot J(t) \rangle$  is the so-called heat-flux autocorrelation function. Our results are carefully tested with respect to the total MD simulation time and the size of the simulation box.

## **III. RESULTS AND DISCUSSIONS**

We begin our discussions with the crystal structures of  $Mg_2Si/Mg_2Sn$  shown in Fig. [1.](#page-1-0) Pristine  $Mg_2Si$  ( $Mg_2Sn$ ) has a face-centered-cubic antifluorite lattice with  $Fm\overline{3}m$  space group. The unit cell contains four primitive cells with the Mg and Si (Sn) atoms located at the 8c: (0.25, 0.25, 0.25) and 4a: (0, 0, 0) sites, respectively. The calculated lattice constants are  $a = 6.35$  and 6.81 Å for the Mg<sub>2</sub>Si and Mg2Sn, respectively. These values are very close to those found experimentally[.26](#page-9-0) The optimized lattice constants of a series of  $Mg_2Si_{1-x}Sn_x$  (0.250  $\leq x \leq 0.875$ ) solid solutions are summarized in Table [I,](#page-1-0) which increases almost linearly from 6.47 to 6.76 Å as the Sn concentration x is increased.<sup>13,27</sup> In particular, the calculated lattice constant ( $a = 6.59$  Å) for the Mg<sub>2</sub>Si<sub>0.5</sub>Sn<sub>0.5</sub> agrees well with the measured value ( $a =$ 6.56 Å), $^{13}$  $^{13}$  $^{13}$  which confirms the reliability of our theoretical calculations.



FIG. 2. (Color online) Calculated energy band structures for a series of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions. The red and blue lines correspond to the light and heavy conduction bands, respectively. The Fermi level is at 0 eV.

## **A. Energy band structure**

<span id="page-3-0"></span>Figures  $2(a)-2(f)$  show the calculated energy band structures for a series of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions. As known, both Mg2Si and Mg2Sn are indirect gap semiconductors. The valence-band maximum (VBM) is located at the  $\Gamma$  point, while the conduction-band minimum (CBM) at the *X* point. However, we see from Fig. [2](#page-2-0) that all the  $Mg_2Si_{1-x}Sn_x$  solid solutions become direct gap semiconductors where both the VBM and the CBM appear at the  $\Gamma$  point. This is due to the fact that we are using a  $2 \times 2 \times 2$  supercell rather than the primitive cell and the bands are thus folded. It should be noted that DFT tends to underestimate the energy gap, therefore, all the calculated band gaps of the  $Mg_2Si_{1-x}Sn_x$  solid solutions are corrected in this work. We find that the difference between experimental $^{26}$  $^{26}$  $^{26}$  and calculated gap is almost the same for the Mg2Si and Mg2Sn. For simplicity, we thus make a uniform shift of the calculated band gaps for all the solid solutions. If we focus on the two low-lying conduction bands around the  $\Gamma$  point, we see that with the Sn content *x* increasing from 0.250 to 0.875, the heavy conduction band  $(CB_H, blue)$ shifts down while the light conduction band  $(CB<sub>L</sub>)$ , red) shifts up. As a result, these two bands converge at  $x = 0.625$ . We have calculated the band-decomposed charge-density contour (not shown here), and find that the lowest conduction band has Si character for the Mg2Si, while Sn character for the Mg<sub>2</sub>Sn. In the case of the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub>, the lowest conduction band exhibits both Si and Sn character; however, the major contribution comes from Si when  $0.25 \le x < 0.625$ , and from Sn when  $0.625 < x \le 0.875$ . This is consistent with

the fact that the lowest conduction band of  $Mg_2Si_{1-x}Sn_x$  is the light band for  $0.25 \le x < 0.625$  but is the heavy band for  $0.625 < x \le 0.875$  (see Fig. [2\)](#page-2-0). At  $x = 0.625$ , the light and heavy bands converge and the charge-density contour indicates that the contributions from Si and Sn are nearly equal to each other. Overall speaking, the effective mass of the lowest conduction band increases with the Sn content *x*, reaches a maximum at  $x = 0.625$ , and then decreases. Both the convergence of the conduction bands and the increased effective mass lead to a high absolute value of the Seebeck coefficient, $1,28$  $1,28$  which is very beneficial to the thermoelectric performance. We will come back to this point later. The energy difference between the  $CB_H$  and  $CB_L$  as well as their effective masses are summarized in Table [I.](#page-1-0)

## **B. Relaxation time and electrical conductivity**

Based on the calculated band structures, we are able to evaluate the electronic transport coefficients of the  $Mg_2Si_{1-x}Sn_x$ solid solutions by using the semiclassical Boltzmann theory and the rigid-band approach. $2<sup>9</sup>$  To get reliable results, we use a very dense *k* mesh up to 1000 points in our calculations. It should be mentioned that the electrical conductivity  $\sigma$  can only be calculated with respect to the electron relaxation time  $\tau$ , that is, what we actually get is  $\sigma/\tau$ . The relaxation time is then determined by comparing the experimentally measured electrical conductivity  $\sigma$  (Ref. [16\)](#page-9-0) at a particular carrier concentration and temperature. The fitted relaxation time for the solid solutions is summarized in Table  $II$ . We see

| $\mathcal{X}$ |                                | $\tau$ (fs) |       |       |       |       |                  |
|---------------|--------------------------------|-------------|-------|-------|-------|-------|------------------|
|               | $n(10^{20}$ cm <sup>-3</sup> ) | 300 K       | 400 K | 500 K | 600 K | 700 K | $800~\mathrm{K}$ |
| 0.25          | 1.70                           | 11.4        | 9.28  | 7.87  | 6.26  | 5.22  | 4.31             |
|               | 2.10                           | 12.3        | 10.1  | 8.13  | 6.85  | 5.7   | 4.43             |
|               | (Mean value)                   | 11.8        | 9.7   | 8.0   | 6.6   | 5.5   | 4.4              |
| 0.375         | 1.35                           | 6.74        | 5.54  | 4.85  | 4.17  | 3.54  | 2.95             |
|               | 1.80                           | 6.32        | 5.27  | 4.31  | 3.76  | 3.23  | 2.74             |
|               | 2.35                           | 6.44        | 5.41  | 4.46  | 3.62  | 3.10  | 2.59             |
|               | (Mean value)                   | 6.5         | 5.4   | 4.5   | 3.8   | 3.3   | 2.8              |
| 0.5           | 1.90                           | 5.43        | 4.62  | 3.84  | 3.39  | 2.74  | 2.37             |
|               | 2.39                           | 3.99        | 3.4   | 2.86  | 2.57  | 2.15  | 1.96             |
|               | 2.84                           | 4.41        | 3.82  | 3.26  | 2.74  | 2.28  | 1.99             |
|               | (Mean value)                   | 4.6         | 3.9   | 3.3   | 2.9   | 2.4   | 2.1              |
| 0.625         | 0.63                           | 7.65        | 6.71  | 5.58  | 4.55  | 4.09  | 3.73             |
|               | 1.68                           | 6.97        | 5.80  | 4.75  | 4.18  | 3.59  | 2.98             |
|               | (Mean value)                   | 7.3         | 6.3   | 5.1   | 4.4   | 3.8   | 3.4              |
| 0.75          | 1.57                           | 6.34        | 5.09  | 4.06  | 3.51  | 2.83  | 2.61             |
|               | 1.69                           | 6.99        | 5.67  | 4.56  | 3.93  | 3.39  | 2.92             |
|               | 1.72                           | 6.78        | 5.96  | 4.79  | 3.83  | 3.30  | 2.84             |
|               | 2.13                           | 6.95        | 5.58  | 4.45  | 3.86  | 3.13  | 1.69             |
|               | (Mean value)                   | 6.8         | 5.6   | 4.5   | 3.8   | 3.2   | 2.5              |
| 0.875         | 1.70                           | 7.87        | 6.44  | 5.14  | 4.06  | 3.41  | 2.87             |
|               | 2.30                           | 8.21        | 6.69  | 5.52  | 4.58  | 3.73  | 2.99             |
|               | (Mean value)                   | 8.0         | 6.6   | 5.3   | 4.3   | 3.6   | 2.9              |

TABLE II. Determining the electron relaxation time  $\tau$  for the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions by comparing the experimentally measured electrical conductivity at different carrier concentration and temperature.

<span id="page-4-0"></span>that the relaxation time does not vary much in the carrierconcentration range considered. In contrast, there is obvious temperature dependence. As a reasonable approximation, in the following discussions we use an average relaxation time at each temperature. For a particular  $x$ , we see from Table [II](#page-3-0) that the relaxation time decreases with increasing temperature. This is reasonable since the electron scattering is more frequent at high temperatures. At a particular temperature, we see that the relaxation time decreases before reaching a minimum value at  $x = 0.5$  and then increases, suggesting that the solid solution at  $x = 0.5$  is of highest disorder as far as the carrier transport is concerned.

Figure  $3(a)$  plots the calculated electrical conductivity  $\sigma$  as a function of temperature for the Mg2Si1<sup>−</sup>*x*Sn*<sup>x</sup>* solid solutions, where the doping level (or carrier concentration) of each system is fixed at  $1.9 \times 10^{20}$  cm<sup>-3</sup>. In the temperature range of 300–800 K, we see that the electrical conductivity decreases with increasing temperature. This is believed to be caused by the reduced electron mobility at high temperatures, while the carrier (electron) concentration remains almost constant with temperature. It is interesting that the calculated  $\sigma$  of  $Mg_2Si_{0.375}Sn_{0.625}$  decreases relatively slower with increasing temperature and is higher than those of the other solid solutions except  $x = 0.250$  and 0.875 at intermediate temperatures. On the other hand, we plot in Fig.  $3(b)$  the calculated electrical conductivity  $\sigma$  as a function of carrier concentration, where the temperature is fixed at 800 K. As expected, the electrical conductivity  $\sigma$  increases with increasing carrier concentration *n*. The electrical conductivity of  $Mg_2Si_{0.750}Sn_{0.250}$ and  $Mg_2Si_{0.375}Sn_{0.625}$  are higher than those of the other solid solutions with Mg<sub>2</sub>Si<sub>0.625</sub>Sn<sub>0.375</sub> and Mg<sub>2</sub>Si<sub>0.500</sub>Sn<sub>0.500</sub> exhibiting the lowest values.

### **C. Seebeck coefficient and power factor**

Figure 4(a) shows the calculated Seebeck coefficient *S* as a function of temperature for the Mg2Si1<sup>−</sup>*x*Sn*<sup>x</sup>* solid solutions at a carrier concentration of  $1.9 \times 10^{20}$  cm<sup>-3</sup>. It is found that the absolute value of the Seebeck coefficient increases with increasing temperature. Compared with the experimentally measured result of Mg2Si0*.*500Sn0*.*500, the calculated *S* exhibits a similar variation with temperature, but the absolute value is somehow underestimated. In Fig.  $4(b)$ , we plot the calculated Seebeck coefficient at 800 K as a function of carrier concentration in the range of  $10^{19}$ – $10^{21}$  cm<sup>-3</sup>. We see the absolute value of Seebeck coefficient increases initially, reaches a maximum, and then decreases as the carrier concentration increases. As mentioned above, when the two conduction bands converge and the effective mass increases, one can obtain a very large absolute value of Seebeck coefficient. Indeed, except at very low carrier concentrations,  $Mg_2Si_{0.375}Sn_{0.625}$  exhibits the highest absolute value of *S* among these solid solutions.

 $-0.250$ 

 $x=0.500$ 

 $= 0.750$ 

 $x=0.375$ 

 $x=0.625$ 

 $x=0.875$ 

 $10^{20}$  /cm

 $x=0.500$  Ref. [16]



 $SWN$  $-200$  $-240$ 300 400 500 600 700 800  $T(K)$  $(b)$  $-200$  $S(uV/K)$  $-300$  $T = 800$  K  $x=0.250$  $x=0.375$  $x=0.500$  $\cdot - x = 0.625$  $x=0.750$  $---x=0.875$  $-400$  $\mathbf{1}$ 10  $0.1$  $n(10^{20}/\text{cm}^3)$ 

FIG. 3. (Color online) (a) Calculated electrical conductivity *σ*of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions as a function of temperature. All systems have a carrier concentration of  $1.9 \times 10^{20}$  cm<sup>-3</sup>. (b) Calculated  $\sigma$  as a function of carrier concentration *n* ( $10^{19}$ – $10^{21}$  cm<sup>-3</sup>) at 800 K.

FIG. 4. (Color online) (a) Calculated Seebeck coefficient *S* of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions as a function of temperature. All systems have a carrier concentration of  $1.9 \times 10^{20}$  cm<sup>-3</sup>, and the measured result of  $Mg_2Si_{0.500}Sn_{0.500}$  is also shown. (b) Calculated *S* as a function of carrier concentration *n* ( $10^{19}$ – $10^{21}$  cm<sup>-3</sup>) at 800 K.

 $(a)$ 

 $-80$ 

 $12($ 

 $-160$ 

<span id="page-5-0"></span>Although there is some underestimation of the calculated Seebeck coefficient, it is still more than 250  $\mu$ V/K for the  $Mg_2Si_{0.375}Sn_{0.625}$  at a carrier concentration of  $10^{20}$  cm<sup>-3</sup>, which is close to those measured previously.<sup>10[,14,30](#page-9-0)</sup> We want to mention that the underestimation of the calculated Seebeck coefficient indicated in Fig.  $4(a)$  can be attributed to the fact that in the experiment,  $16$  the sample prepared deviates a little from the standard nominal formula of  $Mg_2Si_{0.5}Sn_{0.5}$  and has a real composition of  $Mg_{2,11}Si_{0.52}Sn_{0.48}Sb_{0.006}$ . Here, the Mg excess was found to increase the absolute value of the Seebeck coefficient.[33](#page-9-0)

Figure  $5(a)$  shows the calculated power factor  $S^2 \sigma$  as a function of temperature for the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions at a carrier concentration of  $1.9 \times 10^{20}$  cm<sup>-3</sup>. As discussed above, the  $Mg_2Si_{0.375}Sn_{0.625}$  exhibits the highest absolute value of Seebeck coefficient *S* due to the band convergence and enhanced effective mass. It also has a relatively higher electrical conductivity  $\sigma$ , especially at intermediate temperatures. Consequently, the power factor of  $Mg_2Si_{0.375}Sn_{0.625}$  is much higher than those of the other solid solutions in the whole temperature range from 300 to 800 K. On the other hand, we plot in Fig.  $5(b)$  the power factor at 800 K as a function of carrier concentration in the range of  $10^{19}$ – $10^{21}$  cm<sup>-3</sup>. As known, the Seebeck coefficient decreases with increasing carrier concentration, while the electrical conductivity increases. In a broad range of carrier concentrations, the power factor should therefore increase initially, reach a maximum value, and then decrease. Within the carrier concentration considered in this work, we see from Fig.  $5(b)$  that the power factor increases monotonously. The calculated value of  $Mg_2Si_{0.375}Sn_{0.625}$  at 800 K is about  $3.1 \times 10^{-3}$  W/mK<sup>2</sup> with a carrier concentration of 1020 cm<sup>−</sup>3, which is somehow higher than that of other  $Mg_2Si$ -based thermoelectric materials.<sup>[15,31,32](#page-9-0)</sup>

#### **D. Electronic thermal conductivity**

We now discuss the electronic thermal conductivity *κe* of the  $Mg_2Si_{1-x}Sn_x$  solid solutions. As mentioned before, the  $κ_e$  can be derived from  $σ$  using Eq. [\(5\).](#page-1-0) Here, the Lorenz number *L* for the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions is estimated based on the Fermi-Dirac statistics noted in Ref. [11](#page-8-0) which attains the fully degenerate value of  $2.45 \times 10^{-8}$  V<sup>2</sup>/K<sup>2</sup> as the carrier concentration reaches typical metallic densities. For the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions, the Lorenz number is found to be  $1.8 \sim 1.9 \times 10^{-8}$  V<sup>2</sup>/K<sup>2</sup> around the carrier concentration of  $10^{20}$  cm<sup>-3</sup> (Refs. [11](#page-8-0) and [33\)](#page-9-0) and is therefore used in our calculations. Figure  $6(a)$  shows the temperature dependence of the calculated  $\kappa_e$  for the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> series at a carrier concentration of  $1.9 \times 10^{20}$  cm<sup>-3</sup>. The general trend observed is an initial mild increase followed by a rather undistinguished maximum and finally a slowly decreasing conductivity. The





FIG. 5. (Color online) (a) Calculated power factor  $S^2\sigma$  of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions as a function of temperature. All systems have a carrier concentration of  $1.9 \times 10^{20}$  cm<sup>-3</sup>. (b) Calculated  $S^2 \sigma$ as a function of carrier concentration *n* ( $10^{19}$ – $10^{21}$  cm<sup>-3</sup>) at 800 K.

FIG. 6. (Color online) (a) Calculated electronic thermal conductivity  $\kappa_e$  of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions as a function of temperature. All systems have a carrier concentration of  $1.9 \times 10^{20}$  cm<sup>-3</sup>. (b) Calculated  $\kappa_e$  as a function of carrier concentration *n* (10<sup>19</sup>–10<sup>21</sup> cm<sup>-3</sup>) at 800 K.

<span id="page-6-0"></span>calculated *κe* of Mg2Si0*.*375Sn0*.*<sup>625</sup> is 1.17 W*/*mK at 300 K and 1.31 W*/*mK at 800 K.

As shown in Fig.  $6(b)$ , the carrier-concentration dependence of the electronic thermal conductivity *κe* at 800 K mimics the behavior of the electrical conductivity  $\sigma$ , i.e., it increases monotonously with increasing carrier concentration. The Mg2Si0*.*750Sn0*.*<sup>250</sup> and Mg2Si0*.*375Sn0*.*<sup>625</sup> solid solutions exhibit higher *κe* than the others in the whole carrier-concentration range from  $10^{19}$  to  $10^{21}$  cm<sup>-3</sup>. Compared with the power factor shown in Fig.  $5(b)$ , the electronic thermal conductivity of Mg<sub>2</sub>Si<sub>0.375</sub>Sn<sub>0.625</sub> decreases faster with decreasing carrier

concentration *n* around 1020 cm<sup>−</sup>3. For example, as *n* decreases from 2.0 to 1.0 × 10<sup>20</sup> cm<sup>-3</sup> at 800 K, the  $\kappa_e$  of  $Mg_2Si_{0.375}Sn_{0.625}$  falls by 48%, while the power factor  $S^2\sigma$  is reduced by only 21%. In the following discussions, we shall see that such a trend is important for optimizing the thermoelectric performance of these solid solutions.

### **E. Lattice thermal conductivity**

To deal with the phonon transport, we have performed MD simulations where a modified Morse potential is constructed

TABLE III. Fitted parameters in the modified Morse potential for the Mg<sub>2</sub>Si, Mg<sub>2</sub>Sn, and Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions.



<span id="page-7-0"></span>

FIG. 7. (Color online) Calculated lattice thermal conductivity *κl* of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> and Sb-doped Mg<sub>2</sub>Si<sub>0.375</sub>Sn<sub>0.625</sub> solid solutions at a temperature range from 300 to 800 K.

by fitting the energy surface from first-principles calculations. Table [III](#page-6-0) lists all the fitted potential parameters used in this work. Our calculated lattice thermal conductivity  $\kappa_l$  of Mg2Si and Mg2Sn is found to be 5.98 and 4.90 W*/*mK at 300 K, respectively. These values are consistent with those measured experimentally<sup>13,26</sup> and thus confirm the reliability of our MD simulations. The calculated  $\kappa_l$  for the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> series is plotted in Fig. 7 in a wide temperature range. We see that the lattice thermal conductivity does not show strong temperature dependence. At any given temperature, the thermal conductivity initially decreases with increasing content of Sn. It reaches a clear minimum at  $x = 0.625$ and then increases. Note that the minimum lattice thermal conductivity is obtained at  $x = 0.625$  rather than at  $x =$ 0.5 where the Si and Sn should be most disordered. The calculated  $\kappa_l$  for Mg<sub>2</sub>Si<sub>0.375</sub>Sn<sub>0.625</sub> is only 1.62 W/mK at 300 K, representing merely 27% of that of the pure Mg2Si. Such significant reduction in the lattice thermal conductivity is primarily a result of the large atomic mass difference between the Sn and Si that gives rise to a strong mass defect scattering. Our calculated variation of the lattice thermal conductivity as a function of Sn content is similar to the previously reported results. [13,16,26](#page-9-0)

## **F. Optimized** *ZT* **value**

With all transport coefficients available, we can now evaluate *ZT* values of the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions according to Eq.  $(1)$ . Figure  $8(a)$  shows the carrier-concentration dependence of the calculated *ZT* values at 800 K. As noted before, good thermoelectric performance requires a power factor  $S^2 \sigma$ as high as possible and a thermal conductivity  $\kappa$ ( =  $\kappa_e$  +  $\kappa_l$ ) as low as possible. With higher  $S^2\sigma$  and lower  $\kappa$  than the other solid solutions, we see that  $Mg_2Si_{0.375}Sn_{0.625}$  exhibits superior thermoelectric performance in the whole carrier-concentration range ( $n = 10^{19} - 10^{21}$  cm<sup>-3</sup>). In particular, a *ZT* value of 1.11 can be achieved at 800 K with a carrier concentration of  $1.2 \times 10^{20}$  cm<sup>-3</sup>. This is consistent with the conjecture that band convergence and the maximum effective mass will lead to enhanced thermoelectric performance. The *ZT*



FIG. 8. (Color online) (a) Calculated  $ZT$  value of  $Mg_2Si_{1-x}Sn_x$ and Sb-doped Mg<sub>2</sub>Si<sub>0.375</sub>Sn<sub>0.625</sub> solid solutions as a function of carrier concentration *n* (1019–1021 cm<sup>−</sup>3) at 800 K. (b) Calculated *ZT* value at optimal carrier concentration of Mg2Si1<sup>−</sup>*x*Sn*<sup>x</sup>* and Sb-doped  $Mg_2Si_{0.375}Sn_{0.625}$  as a function of temperature.

values of other  $Mg_2Si_{1-x}Sn_x$  solid solutions, together with the optimal carrier concentration *n*, the power factor  $S^2 \sigma$ , and the electronic and lattice thermal conductivities  $\kappa_e$  and  $\kappa_l$  are listed in Table [IV.](#page-8-0)

Figure 8(b) plots the *ZT* values of these solid solutions as a function of temperature at optimal carrier concentrations. We see that the *ZT* values increase from 300 to 800 K, which is consistent with those found previously.[12,14–16](#page-9-0) Moreover, all the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions exhibit higher  $ZT$  values at 800 K than at lower temperatures, which indicates that they could be applied as thermoelectric materials at intermediate temperatures. The optimized *ZT* value of 1.11 achieved at 800 K with Mg<sub>2</sub>Si<sub>0.375</sub>Sn<sub>0.625</sub> is by far the highest value among all the solid solutions.

Although a *ZT* value of 1.11 at 800 K is close to the maximum experimental value reported, $10,14,16,33$  $10,14,16,33$  this is a very conservative value and we believe the thermoelectric performance of *n*-type Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions could be further enhanced. It should be mentioned that up to now, we were considering electron and phonon transport in pristine Mg2Si1<sup>−</sup>*x*Sn*<sup>x</sup>* solid solutions. In real experiments, however, the different carrier concentrations are actually realized by doping these systems with Bi or Sb. According to previous experi-mental works,<sup>9,[16,30,32](#page-9-0)</sup> appropriate doping not only enhances

| $\mathcal{X}$      | $n(10^{20}$ cm <sup>-3</sup> ) | $S^2 \sigma$ (10 <sup>-3</sup> W/mK <sup>2</sup> ) | $\kappa_e$ (W/mK) | $\kappa_l$ (W/mK) | ZΤ   |
|--------------------|--------------------------------|--|-------------------|-------------------|------|
| 0.250              | 4.5                            | 5.20   | 3.54              | 3.79              | 0.57 |
| 0.375              | 3.6                            | 3.32   | 1.86              | 4.00              | 0.45 |
| 0.500              | 2.7                            | 2.54   | 1.18              | 3.66              | 0.42 |
| 0.625              | 1.2                            | 3.24   | 0.85              | 1.48              | 1.11 |
| $0.625$ (Sb-doped) | 1.1                            | 3.15   | 0.78              | 1.25              | 1.24 |
| 0.750              | 2.1                            | 2.83   | 1.16              | 2.27              | 0.66 |
| 0.875              | 2.0                            | 3.10   | 1.38              | 2.77              | 0.60 |

<span id="page-8-0"></span>TABLE IV. Optimized *ZT* values of  $Mg_2Si_{1-x}Sn_x$  as well as Sb-doped  $Mg_2Si_{0.375}Sn_{0.625}$  solid solutions at 800 K. The corresponding optimal carrier concentration *n*, the power factor  $S^2 \sigma$ , and the electronic and lattice thermal conductivity *κ<sub>e</sub>* and *κ<sub>l</sub>* are also indicated.

the power factor  $S^2 \sigma$ , but can also significantly reduce the lattice thermal conductivity  $\kappa_l$  of Mg<sub>2</sub>Si-based thermoelectric materials. To make a better comparison between our theoretical predications and the experimental results, we have done additional calculations where the lattice thermal conductivity *κ*<sub>*l*</sub> of properly Sb-doped Mg<sub>2</sub>Si<sub>0.375</sub>Sn<sub>0.625</sub> is explicitly calculated. Indeed, it is found that  $\kappa_l$  is decreased by about 15% (see Fig. [7\)](#page-7-0). As a result, the optimal carrier concentration is shifted to a value somewhat smaller than  $1.1 \times 10^{20}$  cm<sup>-3</sup> as indicated in Fig.  $8(a)$ . At such carrier concentration, the power factor  $S^2\sigma$  is slightly reduced from 3.24 to 3.15  $\times$ 10<sup>−</sup><sup>3</sup> W*/*mK2. However, there is a faster decrease of the corresponding electronic thermal conductivity *κe* (from 0.85 to 0.78 W*/*mK), leading to a higher *ZT* value of 1.24 as indicated in both Fig.  $8(a)$  and Table IV. We want to emphasize that the lattice thermal conductivity  $\kappa_l$  of the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions could be further reduced by many other means such as isotope doping<sup>34</sup> and embedded nanoinclusions,  $35-37$  which leave the power factor  $S^2 \sigma$  less affected. If the lattice thermal conductivity could be reduced to ~0.8 W/mK,<sup>16</sup> the optimized  $ZT$  values of  $Mg_2Si_{0.375}Sn_{0.625}$  should reach 1.61 at 800 K, which would be very competitive, especially given the low cost and minimal environmental impact of this material system.

#### **IV. SUMMARY**

In summary, we have studied the thermoelectric properties of Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> (0.250  $\le x \le 0.875$ ) solid solutions using a multiscale approach. The convergence of the two conduction bands and the increased electron effective mass lead to a high value of the Seebeck coefficient for  $x = 0.625$ , which has been confirmed by explicit calculations of the electronic transport coefficients. On the other hand,  $Mg_2Si_{0.375}Sn_{0.625}$ exhibits the lowest lattice thermal conductivity among all the solid solutions considered due to the high alloy disorder and a large Sn/Si mass difference scattering. Our theoretical results indicate that the maximum *ZT* value of  $Mg_2Si_{1-x}Sn_x$  solid solutions is ∼1.24 at 800 K for  $x = 0.625$  with a carrier concentration of  $n = 1.1 \times 10^{20}$  cm<sup>-3</sup>. Moreover, we find that the*ZT* value is limited by the high lattice thermal conductivity, which for some solid solutions is as high as 4.0 W*/*mK. Therefore, there is still room to improve the thermoelectric performance of the Mg<sub>2</sub>Si<sub>1−*x*</sub>Sn<sub>*x*</sub> solid solutions. In any case, the *n*-type  $Mg_2Si_{0.375}Sn_{0.625}$  is a very promising thermoelectric material, and major effort should be directed to developing comparatively effective *p*-type  $Mg_2Si_{1-r}Sn_r$  solid solutions so that efficient thermoelectric modules based on this inexpensive and environmentally friendly material system could be realized.

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